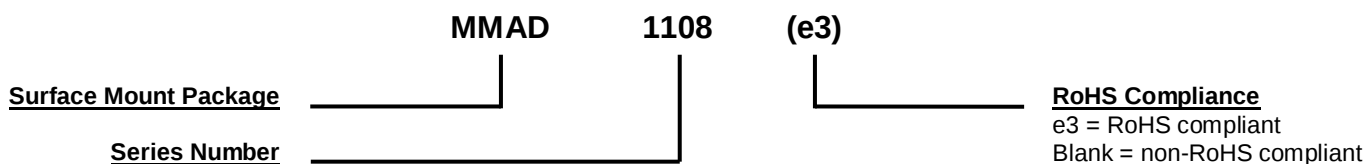


MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T_J and T_{STG}	-55 to +150	°C/W
Peak Working Reverse Voltage	V_{RWM}	75	V
Repetitive Peak Forward Current (one diode)	I_{FRM}	400	mA
Forward Surge Current @ 8.3 ms	I_{FSM}	2	A
@ 8/20 μ s		12	
Rated Average Power Dissipation (total package)	$P_{M(AV)}$	1500	mW
Solder Temperature @ 10 s		260	°C

MECHANICAL and PACKAGING

- CASE: Void-free transfer molded thermosetting epoxy body meeting UL94V-0 flammability classification.
- TERMINALS: Tin-lead or RoHS compliant annealed matte-tin plating solderable per MIL-STD-750 method 2026.
- MARKING: MSC logo, MMAD1108 or MMAD1108e3 and date code. Pin #1 is to the left of the dot or indent on top of package.
- DELIVERY option: Tape and reel or carrier tube. Consult factory for quantities.
- WEIGHT: Approximately 0.127 grams
- See [Package Dimensions](#) on last page.

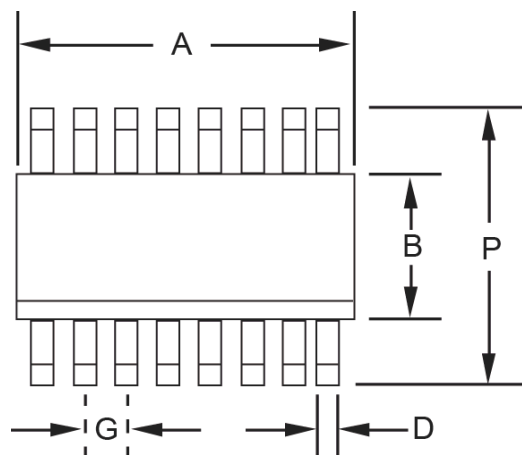
PART NOMENCLATURE

SYMBOLS & DEFINITIONS

Symbol	Definition
C_T	Total Capacitance: The total small signal capacitance between the diode terminals of a complete device.
I_R	Maximum Leakage Current: The maximum leakage current that will flow at the specified voltage and temperature.
$V_{(BR)}$	Breakdown Voltage: The voltage across the device at a specified current $I_{(BR)}$ in the breakdown region.
V_F	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
V_{RWM}	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range.

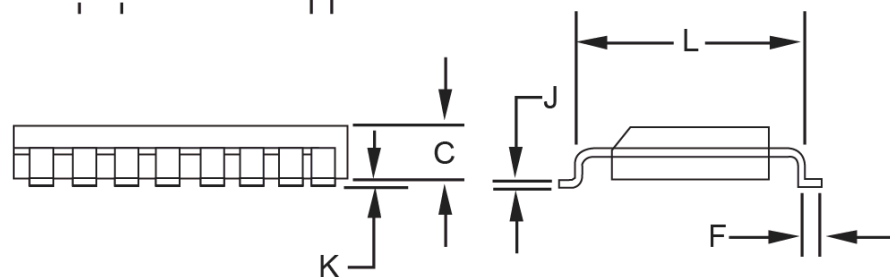
ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise stated

PART NUMBER	BREAKDOWN VOLTAGE $V_{(BR)}$ @ $I_{(BR)} = 100 \mu A$	LEAKAGE CURRENT I_R $T_A = 25 \text{ } ^\circ C$		LEAKAGE CURRENT I_R $T_A = 150 \text{ } ^\circ C$		TOTAL CAPACITANCE C_T @ 0 V	REVERSE RECOVERY TIME t_{rr}	FORWARD VOLTAGE V_F $I_F = 10 \text{ mA}$	FORWARD VOLTAGE V_F $I_F = 100 \text{ mA}$
	V	μA		μA		pF	ns	V	V
	MIN	MAX	@ V_R	MAX	@ V_R	TYP	MAX	MAX	MAX
MMAD1108 MMAD1108e3	90	0.200	20	300	20	1.5	5.0	1.00	1.20

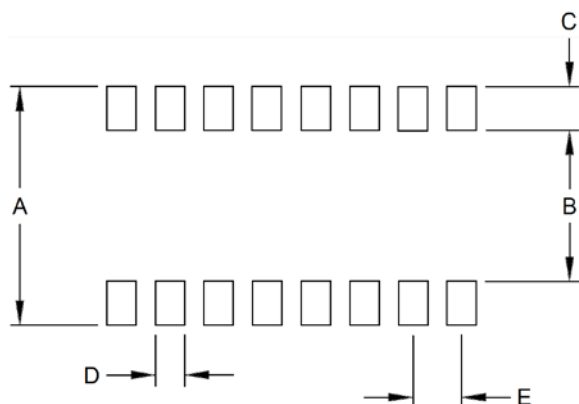
PACKAGE DIMENSIONS



Ref.	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
A	0.358	0.398	9.09	10.10
B	0.150	0.158	3.81	4.01
C	0.053	0.069	1.35	1.75
D	0.011	0.021	0.28	0.53
F	0.016	0.050	0.41	1.27
G	0.050 BSC		1.27 BSC	
J	0.006	0.010	0.15	0.25
K	0.004	0.008	0.10	0.20
L	0.189	0.206	4.80	5.23
P	0.228	0.244	5.79	6.19



PAD LAYOUT



Ref.	Dimensions	
	Inch Typical	Millimeters Typical
A	0.275	7.0
B	0.155	4.0
C	0.060	1.52
D	0.024	0.6
E	0.050	1.270

SCHEMATIC AND CIRCUIT

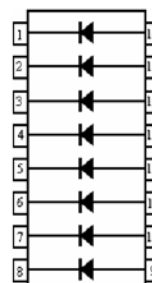
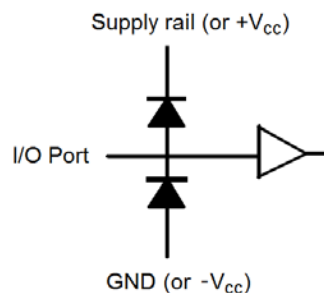


Figure 1